

Title (en)
HEAT PUMP DEVICE

Title (de)
WÄRMEPUMPENVORRICHTUNG

Title (fr)
DISPOSITIF DE POMPE À CHALEUR

Publication
EP 2407736 A1 20120118 (EN)

Application
EP 10750810 A 20100309

Priority
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Abstract (en)
A heat pump apparatus that is capable of suppressing an increase in the installation area therefor and volume thereof is provided. A heat pump apparatus (1) includes a compressor (5) that compresses refrigerant, a condenser (2) that liquefies the compressed refrigerant, and an evaporator (4) that evaporates the liquefied refrigerant, wherein the condenser (2) and the evaporator (4) are plate-type heat exchangers formed in rectangular cuboid shapes, and the condenser (2), which is a plate-type heat exchanger, and the evaporator (4), which is a plate-type heat exchanger, are disposed next each other.

IPC 8 full level
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